

**AMENDMENTS TO THE SPECIFICATION**

**In the Specification:**

Please replace the paragraph beginning at page 3, line 11, with the following rewritten paragraph:

The lower surfaces of the down set portions of at least one die package in the stack [is] may be soldered to the upper surfaces of the down set portions of an adjacent die package in the stack. In one embodiment, solder balls are be attached to the down set portions of the packages prior to stacking the packages. The packages in the stack may be adhered together prior to being soldered. The sides of the encapsulant may be tapered, and the plurality of leads may be disposed on two or more sides of the central region.

Please replace the paragraph beginning at page 6, line 8, with the following rewritten paragraph:

As shown in FIGS. 2A and 2B, a plurality of semiconductor dice 30 are positioned within the central regions 12 of lead frames 10. Each of the dice 30 includes a top surface 32 and a bottom surface 34. The carrier 20 supports the bottom surface 34 of the die 30. It should be appreciated that each of the plurality of semiconductor dice 30 are disposed in central regions 12 such that the bottom surface [32] 34 of each die 30 is substantially coplanar with a bottom surface 14 of the lead frame 10